

## Reliability and Test Condition

Item	Performance	Test Condition
<b>Electrical Performance Test</b>		
Z(common mode)	Refer to standard electrical characteristics list.	Agilent-4291A+ Agilent -16197A
RDC		Agilent-4338B
I.R.		Agilent4339
Temperature Rise Test	Rated Current $\Delta T$ 40°C Max	1.Applied the allowed DC current. 2.Temperature measured by digital surface thermometer
Operating Temperature	-40°C~+125°C (Including self - temperature rise)	
Storage Temperature	-40~+125°C (on board)	
<b>Reliability Test</b>		
Life Test	Appearance : No damage. Impedance : within±15% of initial value RDC : within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 3 times. ( IPC/JEDEC J-STD-020E Classification Reflow Profiles) Temperature : 125±2°C (Inductor) Applied current : rated current Duration : 1000±12hrs Measured at room temperature after placing for 24±2 hrs
Load Humidity		Preconditioning: Run through IR reflow for 3 times. ( IPC/JEDEC J-STD-020E Classification Reflow Profiles) Humidity : 85±2% R.H Temperature : 85°C±2°C Duration : 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs
Moisture Resistance		Preconditioning: Run through IR reflow for 3 times. ( IPC/JEDEC J-STD-020E Classification Reflow Profiles) 1. Baked at 50°C for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs. 3. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs, keep at 25°C for 2 hrs then keep at -10°C for 3 hrs 4. Keep at 25°C 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 3 times. ( IPC/JEDEC J-STD-020E Classification Reflow Profiles) Condition for 1 cycle Step1 : -40±2°C 30±5min Step2 : 25±2°C ≤0.5min Step3 : 125±2°C 30±5min Number of cycles : 500 Measured at room temperature after placing for 24±2 hrs
Vibration		Oscillation Frequency: 10Hz~2KHz~10Hz for 20 minutes Equipment : Vibration checker Total Amplitude: 10g Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations)

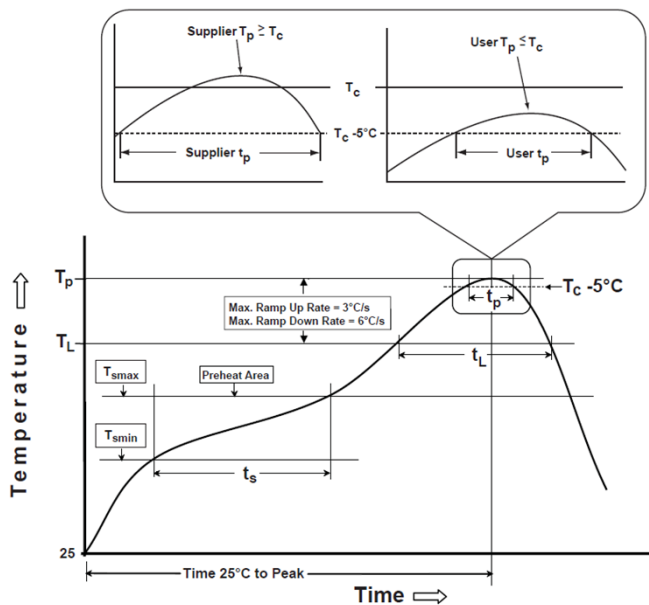
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<b>Reliability Test</b>																	
Shock	Appearance : No damage. Impedance : within±15% of initial value RDC : within ±15% of initial value and shall not exceed the specification value	<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th>Type</th> <th>Peak value (g's)</th> <th>Normal duration (D) (ms)</th> <th>Wave form</th> <th>Velocity change (Vi)ft/sec</th> </tr> </thead> <tbody> <tr> <td>SMD</td> <td style="text-align: center;">50</td> <td style="text-align: center;">11</td> <td style="text-align: center;">Half-sine</td> <td style="text-align: center;">11.3</td> </tr> <tr> <td>Lead</td> <td style="text-align: center;">50</td> <td style="text-align: center;">11</td> <td style="text-align: center;">Half-sine</td> <td style="text-align: center;">11.3</td> </tr> </tbody> </table>	Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec	SMD	50	11	Half-sine	11.3	Lead	50	11	Half-sine	11.3
Type		Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec												
SMD	50	11	Half-sine	11.3													
Lead	50	11	Half-sine	11.3													
Bending		Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.															
Soderability	More than 95% of the terminal electrode should be covered with solder	a. Method B, 4 hrs @155°C dry heat @235°C±5°C Test time:5 +0/-0.5 seconds. b. Method D category 3. (steam aging 8hours ± 15 min) @ 260°C±5°C Test time: 30 +0/-0.5 seconds.															
Resistance to Soldering Heat		Depth: completely cover the termination <table border="1" style="width: 100%; border-collapse: collapse; margin-top: 10px;"> <thead> <tr> <th>Temperature (°C)</th> <th>Time (s)</th> <th>Temperature ramp/immersion and emersion rate</th> <th>Number of heat cycles</th> </tr> </thead> <tbody> <tr> <td style="text-align: center;">260 ±5 (solder temp)</td> <td style="text-align: center;">10 ±1</td> <td style="text-align: center;">25mm/s ±6 mm/s</td> <td style="text-align: center;">1</td> </tr> </tbody> </table>	Temperature (°C)	Time (s)	Temperature ramp/immersion and emersion rate	Number of heat cycles	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	1							
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Terminal Strength	Appearance : No damage. Impedance : within±15% of initial value RDC : within ±15% of initial value and shall not exceed the specification value	Preconditioning:Run through IR reflow for 3 times ( IPC/JEDEC J-STD-020E Classification Reflow Profiles) With the component mounted on a PCB with the device to be tested, apply a force (>0805:1kg , <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested. <div style="text-align: center; margin-top: 20px;"> </div>															
Note : When there are questions concerning measurement result measurement shall be made after 48 ± 2 hours Of recovery under the standard condition.																	

## Reliability and Test Condition

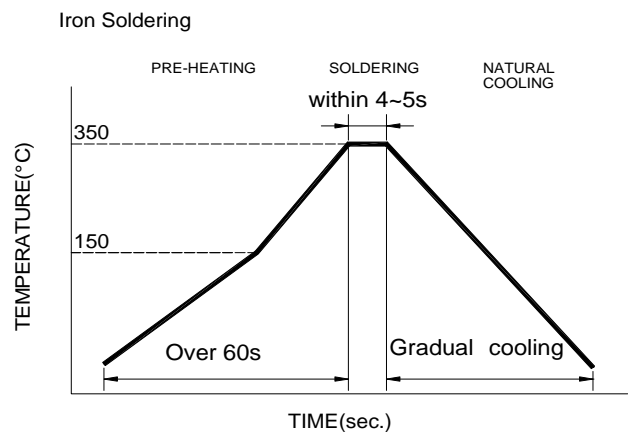
Item	Performance	Test Condition
<b>Soldering and Mounting</b>		
Soldering	Mildly activated rosin fluxes are preferred. JANTEK terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.	
IR Soldering Reflow:	Recommended temperature profiles for lead free re-flow soldering in Figure 1. Table 1.1&1.2 (J-STD-020E)	
Soldering Iron:	<p>Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended. (Figure 2.)</p> <p>Note :</p> <ul style="list-style-type: none"> <li>• Preheat circuit and products to 150°C</li> <li>• Never contact the ceramic with the iron tip</li> <li>• Use a 20 watt soldering iron with tip diameter of 1.0mm</li> <li>• 350°C tip temperature (max)</li> <li>• 1.0mm tip diameter (max)</li> <li>• Limit soldering time to 4~5 sec</li> </ul>	

Fig.1 Soldering Reflow



Reflow times: 3 times max

Fig.2 Iron Reflow



Iron Soldering times : 1 times max

Soldering iron Method : 350± 5°C



## Soldering Specifications

**Table (1.1): Reflow Profiles**

Profile Type:	Pb-Free Assembly
Preheat	
-Temperature Min( $T_{smin}$ )	150°C
-Temperature Max( $T_{smax}$ )	200°C
-Time( $t_s$ )from( $T_{smin}$ to $T_{smax}$ )	60-120seconds
Ramp-up rate( $T_L$ to $T_p$ )	3°C/second max.
Liquidus temperature( $T_L$ )	217°C
Time( $t_L$ )maintained above $T_L$	60-150 seconds
Classification temperature( $T_c$ )	See Table (1.2)
Time( $t_p$ ) at $T_c- 5^\circ\text{C}$ ( $T_p$ should be equal to or less than $T_c$ .)	< 30 seconds
Ramp-down rate( $T_p$ to $T_L$ )	6°C /second max.
Time 25°C to peak temperature	8 minutes max.

**T<sub>p</sub>**: maximum peak package body temperature, **T<sub>c</sub>**: the classification temperature.

For user (customer) **T<sub>p</sub>** should be equal to or less than **T<sub>c</sub>**.

**Table (1.2) Package Thickness/Volume and Classification Temperature( $T_c$ )**

	Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

Reflow is referred to standard IPC/JEDEC J-STD-020E